



**THE DATASHEET OF
8Q-24.000MDDQ-T**



Features

- Frequency range : 24MHz to 66MHz
- Ultra compact and thin
- AuSn sealing, ceramic SMD package
- External dimensions (mm)
L : 1.6 x W : 1.2 x H : 0.35
- RoHS compliant & Pb free

Applications

- BT, BLE, W-LAN, NFC
- SiP modules
- Mobile phone, Wearables
- Internet of Things (IoT)
- Portable consumer products

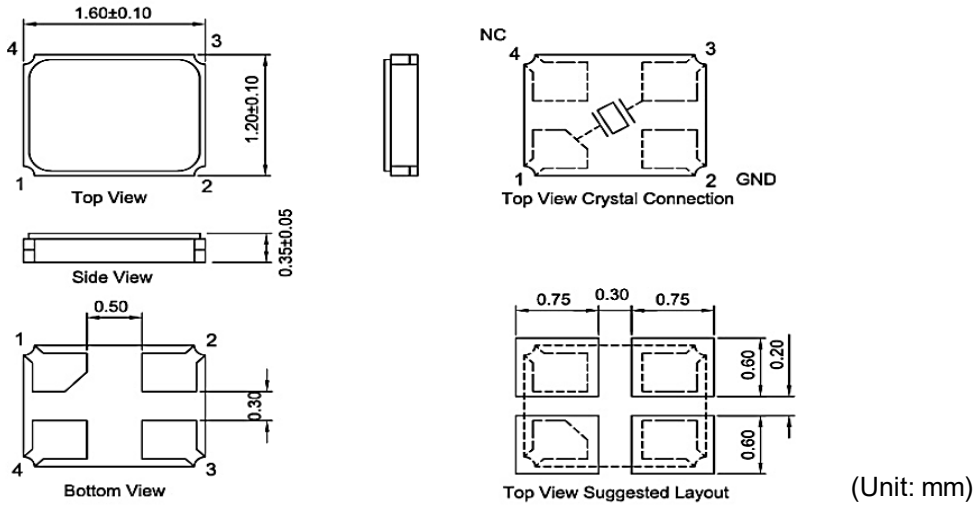
Electrical Characteristics

Item		8Q	Conditions
Frequency Range	F_0	24MHz ~ 66MHz	
Frequency Tolerance	F_{tol}	$\pm 30\text{ppm}$, $\pm 20\text{ppm}$, $\pm 10\text{ppm}$	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	F_{stab}	$\pm 30\text{ ppm}$	-20°C ~ +70°C
		$\pm 20\text{ ppm}$	
		$\pm 10\text{ ppm}$	
		$\pm 10\text{ ppm}$	-30°C ~ +85°C
		$\pm 30\text{ ppm}$	-40°C ~ +85°C
		$\pm 20\text{ ppm}$	
Operating Temperature Range	T_{OTR}	-20°C ~ +70°C	
		-40°C ~ +85°C	
		-40°C ~ +125°C	
Shunt Capacitance	C_0	3pF Max.	
Drive Level	D_L	1 ~ 200 μ W (50 μ W Typ.)	
Load Capacitance	C_L	6pF, 7pF, 8pF, 9pF, 10pF, 12pF, 16pF, 18pF	
Aging	F_{aging}	$\pm 3\text{ ppm Max.}$	at 25°C \pm 3°C, first year
Storage Temperature Range	T_{STR}	-55°C ~ +125°C	

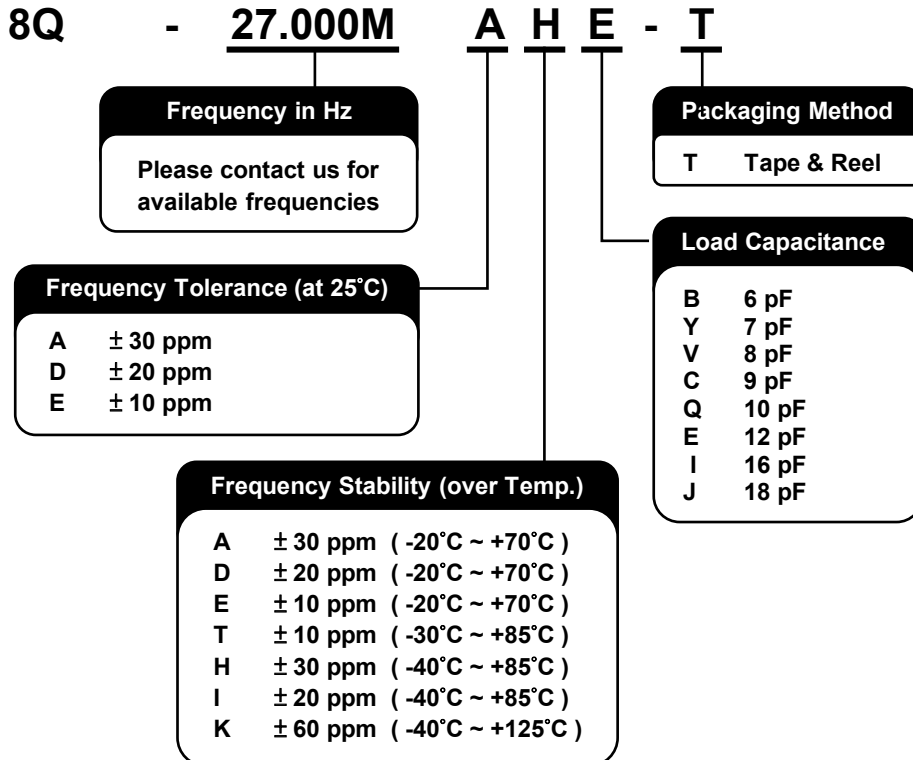
Motional Resistance (ESR)

Fundamental	
24 ~ 30 MHz	100 Ω Max.
30 ~ 66 MHz	80 Ω Max.

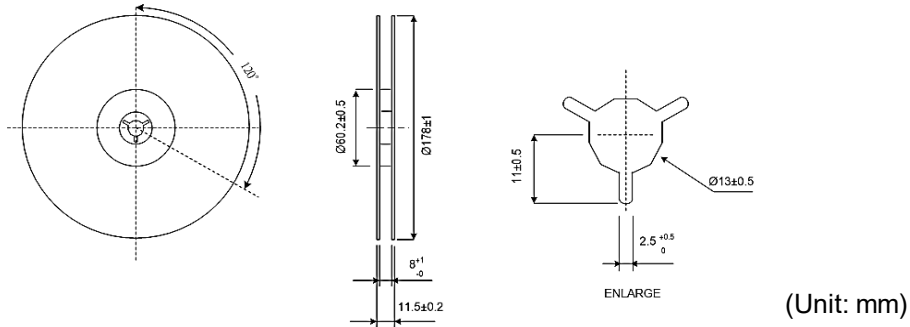
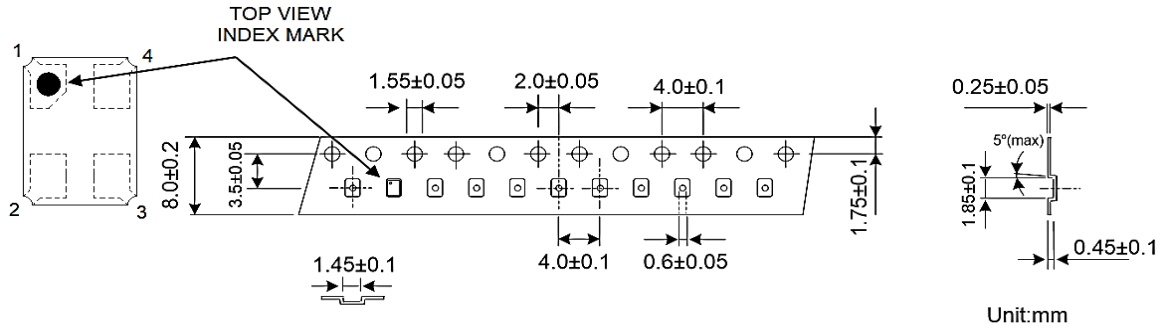
Dimensions



Ordering Information



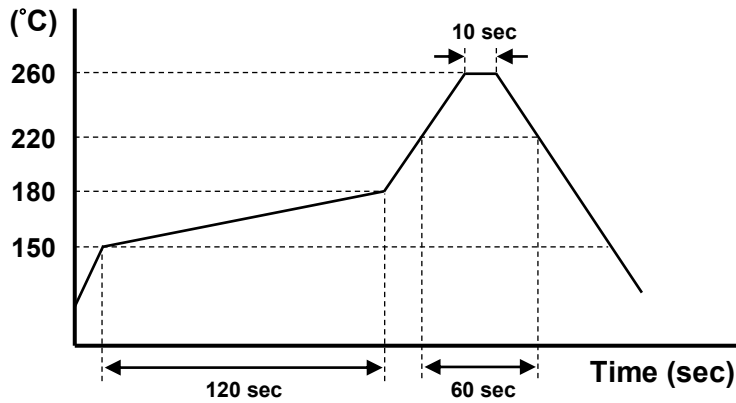
Packing



Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.





Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

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 [TXC CORPORATION](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

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-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management